

View Online at https://aerobasegroup.com/nsn/5910-01-285-8016

Body Style:	
Chip type	
Reliability Indicator:	
Established	
Reliability Failure Rate Level In Percent:	
0.001	
Terminal Length:	
Between 0.3 millimeters and 0.7 millimeters	
Body Length:	
Between 1.8 millimeters and 2.2 millimeters	
Body Width:	
Between 1.0 millimeters and 1.4 millimeters	
Body Height:	
1.3 millimeters	
Schematic Diagram Designator:	
No common or grounded electrode (s)	
Insulation Resistance At Maximum Operating Temp:	
10000.0 megohms	
Capacitance Value Per Section:	
- 12000.000 picofarads single section	
Voltage Tempurature Limits Per Section In Percent Capacitance Change:	
-25.0/+15.0 with rated voltage applied single section	
Nonderated Operating Temp:	
Between -55.0 degrees celsius and 125.0 degrees celsius	
Nonderated Continuous Voltage Rating And Type Per Section:	
50.0 dc single section	
Tolerance Range Per Section:	
-10.00/+10.00 percent single section	
Case Material:	
Ceramic	
Insulation Resistance At Reference Temp:	
100000.0 megohms	
Dissipation Factor At Reference Tempurature In Percent:	
2.500	
Terminal Surface Treatment:	
Solder	
Test Data Document:	
81349-mil-c-55681 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification	ation
format; excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data on certain	
environmental and performance requirements and test conditions that are shown as "typical", "average", "", etc.).	
Terminal Type And Quantity:	
2 bonding pad	

Specification Data:



Shelf Life:

N/a

Unit Of Measure:

Demilitarization:

No

Fiig:

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